

Clmpto
01252006
PY

16. A vacuum microdevice package comprising:

a first cover, the first cover having a first surface including a recessed portion with one or more bond pads;
a second dielectric cover, the second dielectric cover aligned with the first dielectric cover;
a center layer sealed between the first surface of the first dielectric cover and the second dielectric cover, the center layer including a microelectronic device and one or more vias aligned with the bond pads on the recessed portion of the first dielectric cover; and
one or more getters deposited through the vias in the center layer and coupled to the one or more bond pads on the first surface of the first dielectric cover to maintain a constant vacuum level within the sealed microdevice package.

17. The package of claim 16 wherein the bond pads on the first surface of the one or more getters are symmetrically distributed on the microelectronic device.

18. The package of claim 16 wherein the first dielectric cover, second dielectric cover and center layer are sealed with a bond.

19. The package of claim 16 wherein the microelectronic device includes a gyroscope.